

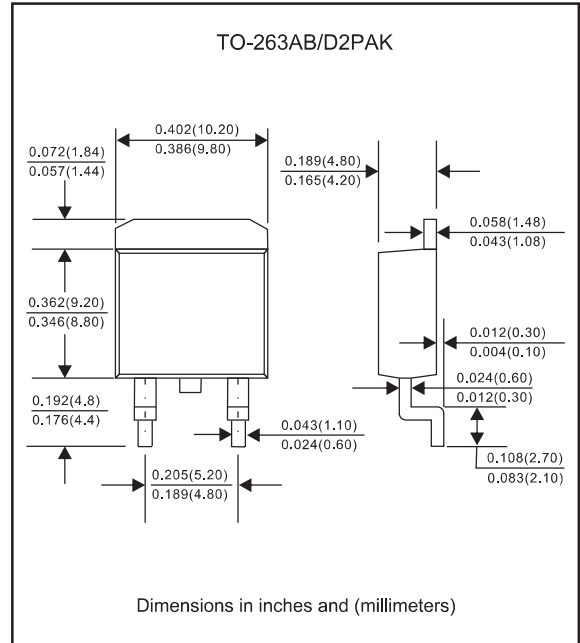
Features

- Batch process design, excellent power dissipation offers better reverse leakage current and thermal resistance.
- Low power loss, high efficiency.
- High current capability, low forward voltage drop.
- High surge capability.
- Guardring for overvoltage protection.
- Ultra high-speed switching.
- Silicon epitaxial planar chip, metal silicon junction.
- Lead-free parts meet environmental standards of MIL-STD-19500 /228
- Suffix "-H" indicates Halogen free parts, ex. MBR3040CG-H-Q1.
- Suffix "-Q1" for AEC-Q101

Mechanical data

- Epoxy:UL94-V0 rated flame retardant
- Case : Molded plastic, TO-263AB / D2PAK
- Terminals : Solder plated, solderable per MIL-STD-750, Method 2026
- Mounting Position : Any

Package outline



Maximum ratings and Electrical Characteristics (AT $T_A=25^{\circ}\text{C}$ unless otherwise noted)

PARAMETER	CONDITIONS	Symbol	MIN.	TYP.	MAX.	UNIT
Forward rectified current	See Fig.1	I_o			30.0	A
Forward surge current	8.3ms single half sine-wave (JEDEC methode)	I_{FSM}			200	A
Reverse current	$V_R = V_{RRM} T_J = 25^{\circ}\text{C}$	I_R			0.1	mA
	$V_R = V_{RRM} T_J = 125^{\circ}\text{C}$				20	
Thermal resistance	Junction to case	$R_{\theta JC}$		1.4		$^{\circ}\text{C}/\text{W}$
Storage temperature		T_{STG}	-65		+175	$^{\circ}\text{C}$

SYMBOLS	V_{RRM}^{*1} (V)	V_{RMS}^{*2} (V)	V_R^{*3} (V)	V_F^{*4} (V)	V_F^{*5} (V)	Operating temperature T_J , ($^{\circ}\text{C}$)
MBR3040CG-Q1	40	28	40	0.70	0.84	-55 to +150
MBR3045CG-Q1	45	31.5	45			
MBR3050CG-Q1	50	35	50	0.80	0.90	
MBR3060CG-Q1	60	42	60			
MBR3080CG-Q1	80	56	80	0.85	0.95	
MBR30100CG-Q1	100	70	100			
MBR30150CG-Q1	150	105	150	0.92	1.00	-55 to +175
MBR30200CG-Q1	200	140	200			

*1 Repetitive peak reverse voltage

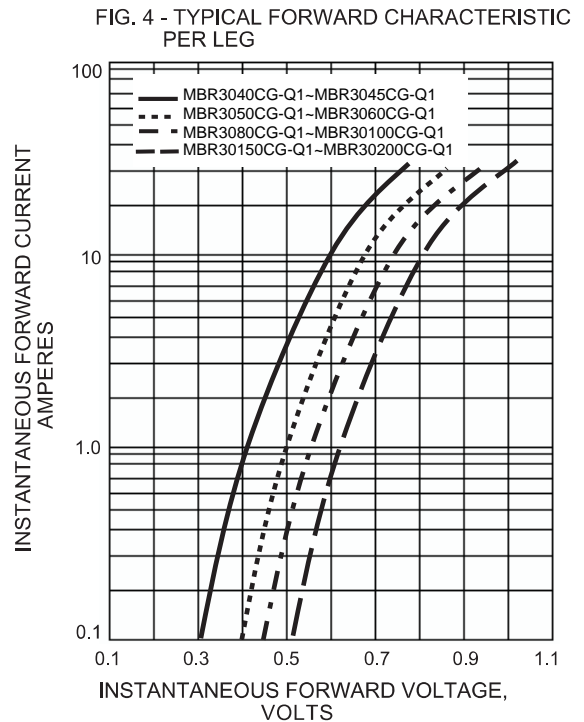
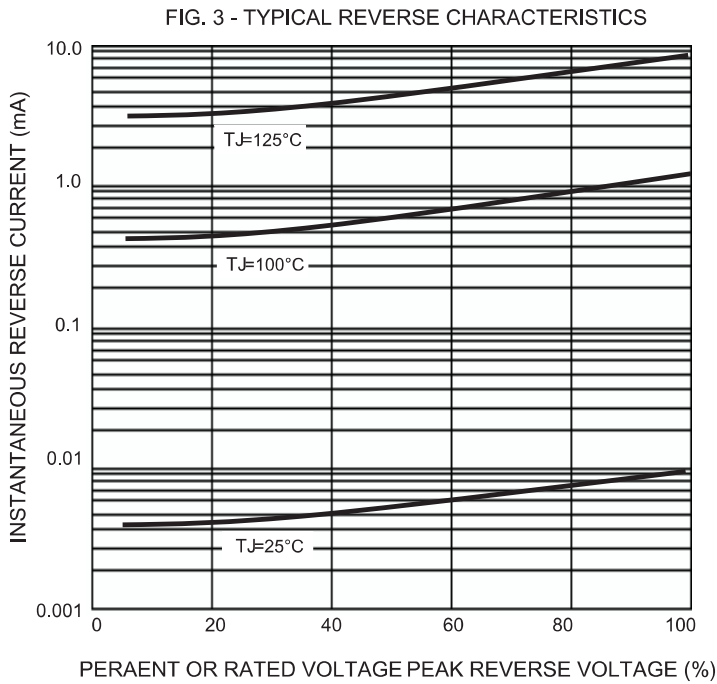
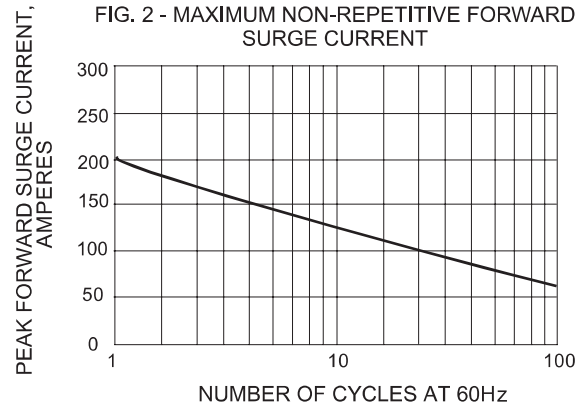
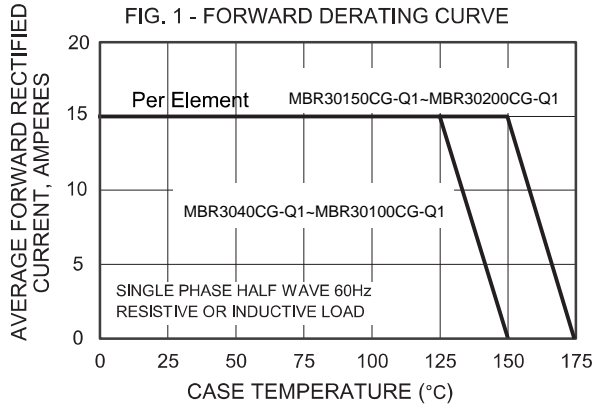
*2 RMS voltage

*3 Continuous reverse voltage

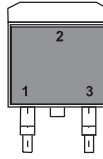
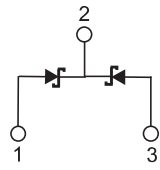
*4 Maximum forward voltage
 $I_F = 15.0\text{A}$, 25°C

*5 Maximum of forward voltage
 $I_F = 30.0\text{A}$, 25°C

Rating and characteristic curves (MBR3040CG-Q1 THRU MBR30200CG-Q1)



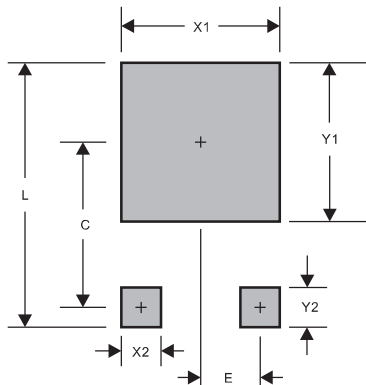
Pinning information

Pin	Simplified outline	Symbol
Pin1 anode Pin2 cathode Pin3 anode		

Marking

Type number	Marking code
MBR3040CG-Q1	MBR3040CG
MBR3045CG-Q1	MBR3045CG
MBR3050CG-Q1	MBR3050CG
MBR3060CG-Q1	MBR3060CG
MBR3080CG-Q1	MBR3080CG
MBR30100CG-Q1	MBR30100CG
MBR30150CG-Q1	MBR30150CG
MBR30200CG-Q1	MBR30200CG

Suggested solder pad layout



PACKAGE	D2PAK
C	0.374(9.50)
E	0.098(2.50)
L	0.665(16.90)
X1	0.425(10.80)
X2	0.071(1.80)
Y1	0.449(11.40)
Y2	0.138(3.50)

Dimensions in inches and (millimeters)